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DATE OF DEPOSIT 10/1/03

Our File No. 9281-4702

Client No. S US02113

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Teruyoshi Kubokawa et al.)
Serial No. To be Assigned)
Filing Date: Herewith)
For Solder Joint Structure and Method for)
Soldering Electronic Components)

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Prior to examination of the above-identified application, please amend the application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks begin on page 6 of this paper.